#### Intel - EP4CE75F29I7 Datasheet





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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

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#### Details

Product Status	Active
Number of LABs/CLBs	4713
Number of Logic Elements/Cells	75408
Total RAM Bits	2810880
Number of I/O	426
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce75f29i7

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Package	_	F169			F324			F484			F672			F896	
Size (mm)		14 × 14		-	19 × 19		:	23 × 23			27 × 27		;	31 × 31	
Pitch (mm)		1.0			1.0			1.0			1.0			1.0	
Device	User I/O	LVDS (2)	XCVRs	User I/O	LVDS (2)	XCVRs	User I/O	LVDS (2)	XCVRs	User I/O	LVDS (2)	XCVRs	User I/O	LVDS (2)	XCVRs
EP4CGX15	▲72	25	2	—	—	—	—	—		—	—	—	—	—	—
EP4CGX22	72	25	2	<b>1</b> 50	64	4	—	—		—	—		—	—	
EP4CGX30	▼72	25	2	<b>▼</b> 150	64	4	▲290	130	4		—		—	—	
EP4CGX50	_	—	_		—	_	290	130	4	<b>4</b> 310	140	8	—	—	—
EP4CGX75	_	—				_	290	130	4	310	140	8		—	—
EP4CGX110	_	_			_	_	270	120	4	393	181	8	<b>▲</b> 475	220	8
EP4CGX150		_	_			_	★270	120	4	▼393	181	8	<b>★</b> 475	220	8

#### Table 1–4. Package Offerings for the Cyclone IV GX Device Family <sup>(1)</sup>

#### Note to Table 1-4:

(1) Use the Pin Migration View window in Pin Planner of the Quartus II software to verify the pin migration compatibility when you perform device migration. For more information, refer to the *I/O Management* chapter in volume 2 of the *Quartus II Handbook*.

(2) This includes both dedicated and emulated LVDS pairs. For more information, refer to the I/O Features in Cyclone IV Devices chapter.

## I/O Features

Cyclone IV device I/O supports programmable bus hold, programmable pull-up resistors, programmable delay, programmable drive strength, programmable slew-rate control to optimize signal integrity, and hot socketing. Cyclone IV devices support calibrated on-chip series termination (Rs OCT) or driver impedance matching (Rs) for single-ended I/O standards. In Cyclone IV GX devices, the high-speed transceiver I/Os are located on the left side of the device. The top, bottom, and right sides can implement general-purpose user I/Os.

Table 1–8 lists the I/O standards that Cyclone IV devices support.

Туре	I/O Standard
Single-Ended I/O	LVTTL, LVCMOS, SSTL, HSTL, PCI, and PCI-X
Differential I/O	SSTL, HSTL, LVPECL, BLVDS, LVDS, mini-LVDS, RSDS, and PPDS

Table 1–8. I/O Standards Support for the Cyclone IV Device Family

The LVDS SERDES is implemented in the core of the device using logic elements.

• For more information, refer to the *I/O Features in Cyclone IV Devices* chapter.

### **Clock Management**

Cyclone IV devices include up to 30 global clock (GCLK) networks and up to eight PLLs with five outputs per PLL to provide robust clock management and synthesis. You can dynamically reconfigure Cyclone IV device PLLs in user mode to change the clock frequency or phase.

Cyclone IV GX devices support two types of PLLs: multipurpose PLLs and generalpurpose PLLs:

- Use multipurpose PLLs for clocking the transceiver blocks. You can also use them for general-purpose clocking when they are not used for transceiver clocking.
- Use general purpose PLLs for general-purpose applications in the fabric and periphery, such as external memory interfaces. Some of the general purpose PLLs can support transceiver clocking.

**Constitution**, refer to the *Clock Networks and PLLs in Cyclone IV Devices* chapter.

## **External Memory Interfaces**

Cyclone IV devices support SDR, DDR, DDR2 SDRAM, and QDRII SRAM interfaces on the top, bottom, and right sides of the device. Cyclone IV E devices also support these interfaces on the left side of the device. Interfaces may span two or more sides of the device to allow more flexible board design. The Altera<sup>®</sup> DDR SDRAM memory interface solution consists of a PHY interface and a memory controller. Altera supplies the PHY IP and you can use it in conjunction with your own custom memory controller or an Altera-provided memory controller. Cyclone IV devices support the use of error correction coding (ECC) bits on DDR and DDR2 SDRAM interfaces.

## **Control Signals**

The clock-enable control signal controls the clock entering the input and output registers and the entire M9K memory block. This signal disables the clock so that the M9K memory block does not see any clock edges and does not perform any operations.

The rden and wren control signals control the read and write operations for each port of M9K memory blocks. You can disable the rden or wren signals independently to save power whenever the operation is not required.

## **Parity Bit Support**

Parity checking for error detection is possible with the parity bit along with internal logic resources. Cyclone IV devices M9K memory blocks support a parity bit for each storage byte. You can use this bit as either a parity bit or as an additional data bit. No parity function is actually performed on this bit.

## **Byte Enable Support**

Cyclone IV devices M9K memory blocks support byte enables that mask the input data so that only specific bytes of data are written. The unwritten bytes retain the previous written value. The wren signals, along with the byte-enable (byteena) signals, control the write operations of the RAM block. The default value of the byteena signals is high (enabled), in which case writing is controlled only by the wren signals. There is no clear port to the byteena registers. M9K blocks support byte enables when the write port has a data width of ×16, ×18, ×32, or ×36 bits.

Byte enables operate in one-hot manner, with the LSB of the byteena signal corresponding to the least significant byte of the data bus. For example, if byteena = 01 and you are using a RAM block in ×18 mode, data[8..0] is enabled and data[17..9] is disabled. Similarly, if byteena = 11, both data[8..0] and data[17..9] are enabled. Byte enables are active high.

Table 3–2 lists the byte selection.

hutaana[2 0]	Affected Bytes							
nareena[20]	datain ×16	datain ×18	datain ×32	datain ×36				
[0] = 1	[70]	[80]	[70]	[80]				
[1] = 1	[158]	[179]	[158]	[179]				
[2] = 1	—	—	[2316]	[2618]				
[3] = 1		—	[3124]	[3527]				

Table 3–2. byteena for Cyclone IV Devices M9K Blocks (1)

Note to Table 3-2:

(1) Any combination of byte enables is possible.



# Figure 5–3. Clock Networks and Clock Control Block Locations in EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 Devices <sup>(1), (2)</sup>

#### Notes to Figure 5-3:

- (1) The clock networks and clock control block locations in this figure apply to only the EP4CGX30 device in F484 package and all EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices.
- (2) PLL 1, PLL 2, PLL 3, and PLL 4 are general purpose PLLs while PLL 5, PLL 6, PLL 7, and PLL 8 are multipurpose PLLs.
- (3) There are 6 clock control blocks on the top, right and bottom sides of the device and 12 clock control blocks on the left side of the device.
- (4) REFCLK[0,1]p/n and REFCLK[4,5]p/n can only drive the general purpose PLLs and multipurpose PLLs on the left side of the device. These clock pins do not have access to the clock control blocks and GCLK networks. The REFCLK[4,5]p/n pins are not available in devices in F484 package.
- (5) Not available for EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices in F484 package.
- (6) Dedicated clock pins can feed into this PLL. However, these paths are not fully compensated.

# **Document Revision History**

Table 5–14 lists the revision history for this chapter.

Table 5-14.	Document	Revision	History
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Date	Version	Changes
October 2012 24		Updated "Manual Override" and "PLL Cascading" sections.
	2.4	Updated Figure 5–9.
November 2011	2.3	<ul> <li>Updated the "Dynamic Phase Shifting" section.</li> </ul>
	2.0	<ul> <li>Updated Figure 5–26.</li> </ul>
		<ul> <li>Updated for the Quartus II software version 10.1 release.</li> </ul>
		<ul> <li>Updated Figure 5–3 and Figure 5–10.</li> </ul>
December 2010	2.2	<ul> <li>Updated "GCLK Network Clock Source Generation", "PLLs in Cyclone IV Devices", and "Manual Override" sections.</li> </ul>
		<ul> <li>Minor text edits.</li> </ul>
		<ul> <li>Updated Figure 5–2, Figure 5–3, Figure 5–4, and Figure 5–10.</li> </ul>
July 2010	2.1	<ul> <li>Updated Table 5–1, Table 5–2, and Table 5–5.</li> </ul>
		<ul> <li>Updated "Clock Feedback Modes" section.</li> </ul>
		<ul> <li>Added Cyclone IV E devices information for the Quartus II software version 9.1 SP1 release.</li> </ul>
		<ul> <li>Updated "Clock Networks" section.</li> </ul>
February 2010	2.0	Updated Table 5–1 and Table 5–2.
		Added Table 5–3.
		<ul> <li>Updated Figure 5–2, Figure 5–3, and Figure 5–9.</li> </ul>
		Added Figure 5–4 and Figure 5–10.
November 2009	1.0	Initial release.

# **High-Speed I/O Interface**

Cyclone IV E I/Os are separated into eight I/O banks, as shown in Figure 6–9 on page 6–17. Cyclone IV GX I/Os are separated into six user I/O banks with the left side of the device as the transceiver block, as shown in Figure 6–10 on page 6–18. Each bank has an independent power supply. True output drivers for LVDS, RSDS, mini-LVDS, and PPDS are on the right I/O banks. On the Cyclone IV E row I/O banks and the Cyclone IV GX right I/O banks, some of the differential pin pairs (p and n pins) of the true output drivers are not located on adjacent pins. In these cases, a power pin is located between the p and n pins. These I/O standards are also supported on all I/O banks using two single-ended output with the second output programmed as inverted, and an external resistor network. True input buffers for these I/O standards are supported on the top, bottom, and right I/O banks except for I/O bank 9.

### Power-On Reset (POR) Circuit

The POR circuit keeps the device in reset state until the power supply voltage levels have stabilized during device power up. After device power up, the device does not release nSTATUS until V<sub>CCINT</sub>, V<sub>CCA</sub>, and V<sub>CCIO</sub> (for I/O banks in which the configuration and JTAG pins reside) are above the POR trip point of the device. V<sub>CCINT</sub> and V<sub>CCA</sub> are monitored for brown-out conditions after device power up.

 $\bigvee$  V<sub>CCA</sub> is the analog power to the phase-locked loop (PLL).

In some applications, it is necessary for a device to wake up very quickly to begin operation. Cyclone IV devices offer the fast POR time option to support fast wake-up time applications. The fast POR time option has stricter power-up requirements when compared with the standard POR time option. You can select either the fast option or the standard POR option with the MSEL pin settings.

- If your system exceeds the fast or standard POR time, you must hold nCONFIG low until all the power supplies are stable.
  - For more information about the POR specifications, refer to the *Cyclone IV Device Datasheet*.
- **For more information about the wake-up time and POR circuit, refer to the** *Power Requirements for Cyclone IV Devices* chapter.

### **Configuration File Size**

Table 8–2 lists the approximate uncompressed configuration file sizes for Cyclone IV devices. To calculate the amount of storage space required for multiple device configurations, add the file size of each device together.

	Device	Data Size (bits)
	EP4CE6	2,944,088
	EP4CE10	2,944,088
	EP4CE15	4,086,848
	EP4CE22	5,748,552
Cyclone IV E	EP4CE30	9,534,304
	EP4CE40	9,534,304
	EP4CE55	14,889,560
	EP4CE75	19,965,752
	EP4CE115	28,571,696

Table 8–2. Uncompressed Raw Binary File (.rbf) Sizes for Cyclone IV Devices (Part 1 of 2)

•••

You can use a download cable to configure multiple Cyclone IV device configuration pins. nCONFIG, nSTATUS, DCLK, DATA[0], and CONF\_DONE are connected to every device in the chain. All devices in the chain utilize and enter user mode at the same time because all CONF\_DONE pins are tied together.

In addition, the entire chain halts configuration if any device detects an error because the nSTATUS pins are tied together. Figure 8–18 shows the PS configuration for multiple Cyclone IV devices using a MasterBlaster, USB-Blaster, ByteBlaster II, or ByteBlasterMV cable.





#### Notes to Figure 8-18:

- (1) You must connect the pull-up resistor to the same supply voltage as the  $V_{CCA}$  supply.
- (2) The pull-up resistors on DATA[0] and DCLK are only required if the download cable is the only configuration scheme used on your board. This ensures that DATA[0] and DCLK are not left floating after configuration. For example, if you also use a configuration device, the pull-up resistors on DATA[0] and DCLK are not required.
- (3) Pin 6 of the header is a V<sub>10</sub> reference voltage for the MasterBlaster output driver. V<sub>10</sub> must match the V<sub>CCA</sub> of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the ByteBlasterMV download cable, this pin is a no connect. When using USB-Blaster, ByteBlaster II, and EthernetBlaster cables, this pin is connected to nCE when it is used for AS programming. Otherwise, it is a no connect.
- (4) Connect the pull-up resistor to the  $V_{CCIO}$  supply voltage of the I/O bank in which the nCE pin resides.
- (5) The nCEO pin of the last device in the chain is left unconnected or used as a user I/O pin.
- (6) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect MSEL for PS configuration schemes, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V<sub>CCA</sub> or GND.
- (7) Power up the V<sub>CC</sub> of the ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5 V supply from V<sub>CCA</sub>. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V<sub>CC</sub> power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

#### ACTIVE\_DISENGAGE

The ACTIVE\_DISENGAGE instruction places the active configuration controller (AS and AP) into an idle state prior to JTAG programming. The two purposes of placing the active controller in an idle state are:

- To ensure that it is not trying to configure the device during JTAG programming
- To allow the controllers to properly recognize a successful JTAG programming that results in the device reaching user mode

The ACTIVE\_DISENGAGE instruction is required before JTAG programming regardless of the current state of the Cyclone IV device if the MSEL pins are set to an AS or AP configuration scheme. If the ACTIVE\_DISENGAGE instruction is issued during a passive configuration scheme (PS or FPP), it has no effect on the Cyclone IV device. Similarly, the CONFIG\_IO instruction is issued after an ACTIVE\_DISENGAGE instruction, but is no longer required to properly halt configuration. Table 8–17 lists the required, recommended, and optional instructions for each configuration mode. The ordering of the required instructions is a hard requirement and must be met to ensure functionality.

	Configuration Scheme and Current State of the Cyclone IV Device											
JTAG Instruction	Prior to User Mode (Interrupting Configuration)				User Mode			Power Up				
	PS	FPP	AS	AP	PS	FPP	AS	AP	PS	FPP	AS	AP
ACTIVE_DISENGAGE	0	0	R	R	0	0	0	R	0	0	R	R
CONFIG_IO	Rc	Rc	0	0	0	0	0	0	NA	NA	NA	NA
Other JTAG instructions	0	0	0	0	0	0	0	0	0	0	0	0
JTAG_PROGRAM	R	R	R	R	R	R	R	R	R	R	R	R
CHECK_STATUS	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc	Rc
JTAG_STARTUP	R	R	R	R	R	R	R	R	R	R	R	R
JTAG TAP Reset/other instruction	R	R	R	R	R	R	R	R	R	R	R	R

#### Table 8–17. JTAG Programming Instruction Flows (1)

Note to Table 8-17:

(1) "R" indicates that the instruction must be executed before the next instruction, "O" indicates the optional instruction, "Rc" indicates the recommended instruction, and "NA" indicates that the instruction is not allowed in this mode.

In the AS or AP configuration scheme, the ACTIVE\_DISENGAGE instruction puts the active configuration controller into idle state. If a successful JTAG programming is executed, the active controller is automatically re-engaged after user mode is reached through JTAG programming. This causes the active controller to transition to their respective user mode states.

If JTAG programming fails to get the Cyclone IV device to enter user mode and re-engage active programming, there are available methods to achieve this:

In AS configuration scheme, you can re-engage the AS controller by moving the JTAG TAP controller to the reset state or by issuing the ACTIVE\_ENGAGE instruction.

- The divisor value divides the frequency of the configuration oscillator output clock. This output clock is used as the clock source for the error detection process.
- 8. Click OK.



Canacitive Loading	Board Trace Model 1/0 Timing
General Configuration Pro	gramming Files   Unused Pins   Dual-Purpose Pin
Voltage Pin	Placement Error Detection CRC
Specify whether error detection Cl	RC is used and the rate at which it is checked.
Enable error detection CRC	
🔲 Enable Open Drain on CRC E	rror pin
Divide error check frequency by:	2
Description:	
Description: Specifies error detection CRC uss is turned on, the device checks t Any changes in the data while th this feature in Stratix, Cyclone, or	age for the selected device. If error detection CRC he validity of the programming data in the device. e device is in operation generates an error. Using Stratix GX will cause a reduction in device speed.
Description: Specifies error detection CRC usa is turned on, the device checks t Any changes in the data while th this feature in Stratix, Cyclone, or	age for the selected device. If error detection CRC he validity of the programming data in the device, e device is in operation generates an error. Using Stratix GX will cause a reduction in device speed.
Description: Specifies error detection CRC usa is turned on, the device checks t Any changes in the data while th this feature in Stratix, Cyclone, or	age for the selected device. If error detection CRC he validity of the programming data in the device. e device is in operation generates an error. Using Stratix GX will cause a reduction in device speed. Reset

## **Accessing Error Detection Block Through User Logic**

The error detection circuit stores the computed 32-bit CRC signature in a 32-bit register, which is read out by user logic from the core. The cycloneiv\_crcblock primitive is a WYSIWYG component used to establish the interface from the user logic to the error detection circuit. The cycloneiv\_crcblock primitive atom contains the input and output ports that must be included in the atom. To access the logic array, the cycloneiv\_crcblock WYSIWYG atom must be inserted into your design.

Chann	el Configuration	Quartus II Selection			
Bonded	With rate match FIFO <sup>(1)</sup>	coreclkout clock feeds the FIFO read clock for the bonded channels. coreclkout clock is the common bonded low-speed clock, which also feeds the FIFO read clock and transmitter PCS in the bonded channels.			
bonded	Without rate match FIFO	<code>rx_clkout</code> clock feeds the FIFO read clock. <code>rx_clkout</code> is forwarded through the receiver channel from low-speed recovered clock, which also feeds the FIFO write clock.			

Table 1–13. Automatic RX Phase Con	pensation FIFO Read Clock Selection	(Part 2 of 2)
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Note to Table 1-13:

(1) Configuration with rate match FIFO is supported in transmitter and receiver operation.

When using user-specified clock option, ensure that the clock feeding rx\_coreclk port has 0 ppm difference with the RX phase compensation FIFO write clock.

# **Calibration Block**

This block calibrates the OCT resistors and the analog portions of the transceiver blocks to ensure that the functionality is independent of process, voltage, and temperature (PVT) variations.

Figure 1–40 shows the location of the calibration block and how it is connected to the transceiver blocks.

#### Figure 1–40. Transceiver Calibration Blocks Location and Connection



#### Note to Figure 1-40:

(1) Transceiver block GXBL1 is only available for devices in F484 and larger packages.

Figure 1–66 shows the transceiver channel datapath and clocking when configured in deterministic latency mode.





Note to Figure 1-66:

(1) High-speed recovered clock.

### **Receive Bit-Slip Indication**

The number of bits slipped in the word aligner for synchronization in manual alignment mode is provided with the rx\_bitslipboundaryselectout [4..0] signal. For example, if one bit is slipped in word aligner to achieve synchronization, the output on rx\_bitslipboundaryselectout [4..0] signal shows a value of 1 (5'00001). The information from this signal helps in latency calculation through the receiver as the number of bits slipped in the word aligner varies at each synchronization.

### **Transmit Bit-Slip Control**

The transmitter datapath supports bit-slip control to delay the serial data transmission by a number of specified bits in PCS with tx\_bitslipboundaryselect[4..0] port. With 8- or 10-bit channel width, the transmitter supports zero to nine bits of data slip. This feature helps to maintain a fixed round trip latency by compensating latency variation from word aligner when providing the appropriate values on tx\_bitslipboundaryselect[4..0] port based on values on rx\_bitslipboundaryselectout[4..0] signal.

### **PLL PFD feedback**

In Deterministic Latency mode, when transmitter input reference clock frequency is the same as the low-speed clock, the PLL that clocks the transceiver supports PFD feedback. When enabled, the PLL compensates for delay uncertainty in the low-speed clock (tx\_clkout in ×1 configuration or coreclkout in ×4 configuration) path relative to input reference and the transmitter datapath latency is fixed relative to the transmitter input reference clock.

### **SDI Mode**

SDI mode provides the non-bonded (×1) transceiver channel datapath configuration for HD- and 3G-SDI protocol implementations.

Cyclone IV GX transceivers configured in SDI mode provides the serialization and deserialization functions that supports the SDI data rates as listed in Table 1–24.

SMPTE Standard <sup>(1)</sup>	Configuration	Data Rate (Mbps)	FPGA Fabric-to- Transceiver Width	Byte SERDES Usage	
292M		1/83 5	20-bit	Used	
	High definition (HD)	1405.5	10-bit	Not used	
		1/95	20-bit	Used	
		1405	10-bit	Not used	
424M	Third-generation (3C)	2967	20_bit	llead	
42411	Thild-generation (30)	2970	20-01	USEU	

Table 1–24. Supported SDI Data Rates

Note to Table 1-24:

(1) Society of Motion Picture and Television Engineers (SMPTE).

SDI functions such as scrambling/de-scrambling, framing, and cyclic redundancy check (CRC) must be implemented in the user logic.

## PRBS

Figure 1–74 shows the datapath for the PRBS, high and low frequency pattern test modes. The pattern generator is located in TX PCS before the serializer, and PRBS pattern verifier located in RX PCS after the word aligner.

Figure 1–74. PRBS Pattern Test Mode Datapath



#### Note to Figure 1-74:

(1) Serial loopback path is optional and can be enabled for the PRBS verifier to check the PRBS pattern

Table 1–25 lists the supported PRBS, high and low frequency patterns, and corresponding channel settings. The PRBS pattern repeats after completing an iteration. The number of bits a PRBS X pattern sends before repeating the pattern is  $2^{(X-1)}$  bits.

Table 1–25. PRBS, High and Low Frequency Patterns, and Channel Settings (Part 1 of 2)

			8-bit Cha	nnel Width		10-bit Channel Width						
Patterns	Polynomial	Channel Width of 8 bits (1)	Word Alignment Pattern	Maximum Data Rate (Gbps) for F324 and Smaller Packages	Maximum Data Rate (Gbps) for F484 and Larger Packages	Channel Width of 10-bits (1)	Word Alignment Pattern	Maximum Data Rate (Gbps) for F324 and Smaller Packages	Maximum Data Rate (Gbps) for F484 and Larger Packages			
PRBS 7	X <sup>7</sup> + X <sup>6</sup> + 1	Y	16'h3040	2.0	2.5	Ν	—	—				
PRBS 8	X <sup>8</sup> + X <sup>7</sup> + 1	Y	16'hFF5A	2.0	2.5	N	—	—				
PRBS 10	$X^{10} + X^7 + 1$	N	—	—	—	Y	10'h3FF	2.5	3.125			
PRBS 23	$X^{23} + X^{18} + 1$	Y	16'hFFFF	2.0	2.5	N	_	_				
High frequency <sup>(2)</sup>	1010101010	Y	_	2.0	2.5	Y	_	2.5	3.125			

#### **Receiver and Transmitter Channel—Receiver CDR in Automatic Lock Mode**

This configuration contains both a transmitter and a receiver channel. If you create a **Receiver and Transmitter** instance in the ALTGX MegaWizard Plug-In Manager with the receiver CDR in automatic lock mode, use the reset sequence shown in Figure 2–8.

Figure 2–8. Sample Reset Sequence of Receiver and Transmitter Channel—Receiver CDR in Automatic Lock Mode



#### Notes to Figure 2-8:

- (1) For t<sub>LTD Auto</sub> duration, refer to the Cyclone IV Device Datasheet chapter.
- (2) The busy signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the busy signal is asserted and deasserted only if there is a read or write operation to the ALTGX\_RECONFIG megafunction.

As shown in Figure 2–8, perform the following reset procedure for the receiver in CDR automatic lock mode:

- 1. After power up, assert pll\_areset for a minimum period of 1 µs (the time between markers 1 and 2).
- 2. Keep the tx\_digitalreset, rx\_analogreset, and rx\_digitalreset signals asserted during this time period. After you deassert the pll\_areset signal, the multipurpose PLL starts locking to the transmitter input reference clock.
- 3. After the multipurpose PLL locks, as indicated by the pll\_locked signal going high (marker 3), deassert tx\_digitalreset. For receiver operation, after deassertion of busy signal, wait for two parallel clock cycles to deassert the rx\_analogreset signal.
- 4. Wait for the rx freqlocked signal to go high (marker 7).
- 5. After the rx\_freqlocked signal goes high, wait for at least t<sub>LTD\_Auto</sub>, then deassert the rx\_digitalreset signal (marker 8). At this point, the transmitter and receiver are ready for data traffic.

If you are reconfiguring the multipurpose PLL with a different M counter value, follow these steps:

- 1. During transceiver PLL reconfiguration, assert tx\_digitalreset, rx\_digitalreset, and rx\_analogreset signals.
- 2. Perform PLL reconfiguration to update the multipurpose PLL with the PLL **.mif** files.
- 3. Perform channel reconfiguration and update the transceiver with the GXB reconfiguration **.mif** files. If you have multiple channel instantiations connected to the same multipurpose PLL, reconfigure each channel.
- 4. Deassert tx\_digitalreset and rx\_analogreset signals.
- 5. After the rx\_freqlocked signal goes high, wait for at least 4 µs, and then deassert the rx\_digitalreset signal.

# **Error Indication During Dynamic Reconfiguration**

The ALTGX\_RECONFIG MegaWizard Plug-In Manager provides an error status signal when you select the **Enable illegal mode checking** option or the **Enable self recovery** option in the **Error checks/data rate switch** screen. The conditions under which the error signal is asserted are:

- Enable illegal mode checking option—when you select this option, the dynamic reconfiguration controller checks whether an attempted operation falls under one of the conditions listed below. The dynamic reconfiguration controller detects these conditions within two reconfig\_clk cycles, deasserts the busy signal, and asserts the error signal for two reconfig\_clk cycles.
  - PMA controls, read operation—none of the output ports (rx\_eqctrl\_out, rx\_eqdcgain\_out, tx\_vodctrl\_out, and tx\_preemp\_out) are selected in the ALTGX\_RECONFIG instance and the read signal is asserted.
  - PMA controls, write operation—none of the input ports (rx\_eqctrl, rx\_eqdcgain, tx\_vodctrl, and tx\_preemp) are selected in the ALTGX\_RECONFIG instance and the write\_all signal is asserted.
- Channel reconfiguration and PMA reconfiguration mode select read operation option:
  - The reconfig\_mode\_sel input port is set to 3'b001 (Channel reconfiguration mode)
  - The read signal is asserted
- Enable self recovery option—when you select this option, the ALTGX\_RECONFIG MegaWizard Plug-In Manager provides the error output port. The dynamic reconfiguration controller quits an operation if it did not complete within the expected number of clock cycles. After recovering from the illegal operation, the dynamic reconfiguration controller deasserts the busy signal and asserts the error output port for two reconfig\_clk cycles.
- The error signal is not asserted when an illegal value is written to any of the PMA controls.

A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit				
Vi		V <sub>1</sub> = 4.20	100	%				
		V <sub>1</sub> = 4.25	98	%				
	AC Input Voltage	V <sub>1</sub> = 4.30	65	%				
		V <sub>1</sub> = 4.35	43	%				
		V <sub>1</sub> = 4.40	29	%				
	Voltago	V <sub>1</sub> = 4.45	20	%				
		$V_1 = 4.50$	13	%				
		V <sub>1</sub> = 4.55	9					
		$V_1 = 4.60$	6	%				

Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as ([delta T]/T) × 100. This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.





## **DC Characteristics**

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

### **Supply Current**

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1–6 lists the I/O pin leakage current for Cyclone IV devices.

Table 1–6. I/O Pin Leakage Current for Cyclone IV Devices (1), (2)

Symbol	Parameter	Conditions	Device	Min	Тур	Max	Unit
I <sub>I</sub>	Input pin leakage current	$V_{I} = 0 V \text{ to } V_{CCIOMAX}$	—	-10	_	10	μΑ
I <sub>OZ</sub>	Tristated I/O pin leakage current	$V_0 = 0 V \text{ to } V_{\text{CCIOMAX}}$	_	-10		10	μA

Notes to Table 1-6:

(1) This value is specified for normal device operation. The value varies during device power-up. This applies for all V<sub>CCI0</sub> settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).

(2) The 10  $\mu$ A I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

### **Bus Hold**

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1–7 lists bus hold specifications for Cyclone IV devices.

 Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) <sup>(1)</sup>

		V <sub>CCIO</sub> (V)												
Parameter	Condition	1.2		1.5		1.8		2.5		3.0		3.3		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold low, sustaining current	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	8	_	12	_	30	_	50	_	70	_	70	_	μΑ
Bus hold high, sustaining current	V <sub>IN</sub> < V <sub>IL</sub> (minimum)	-8	_	-12	_	-30	_	-50	_	-70	_	-70	_	μΑ
Bus hold low, overdrive current	$0 V < V_{IN} < V_{CCIO}$		125	_	175	_	200	_	300	_	500	_	500	μA
Bus hold high, overdrive current	$0 \text{ V} < \text{V}_{\text{IN}} < \text{V}_{\text{CCIO}}$		-125		-175		-200		-300		-500		-500	μA

1-7

# **Transceiver Performance Specifications**

Table 1–21 lists the Cyclone IV GX transceiver specifications.

#### Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 1 of 4)

Symbol/	Oonditions	C6				C7, I7			11			
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIII	
Reference Clock												
Supported I/O Standards	1.2 V PCML, 1.5 V PCML, 3.3 V PCML, Differential LVPECL, LVDS, HCSL											
Input frequency from REFCLK input pins	_	50	_	156.25	50	_	156.25	50	_	156.25	MHz	
Spread-spectrum modulating clock frequency	Physical interface for PCI Express (PIPE) mode	30	_	33	30	_	33	30	_	33	kHz	
Spread-spectrum downspread	PIPE mode	_	0 to 0.5%	_	_	0 to 0.5%	_	_	0 to 0.5%	_	_	
Peak-to-peak differential input voltage	_	0.1	_	1.6	0.1	_	1.6	0.1	_	1.6	V	
V <sub>ICM</sub> (AC coupled)	—		1100 ± 5	5%		1100 ± 59	%	1100 ± 5%			mV	
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV	
Transmitter REFCLK Phase Noise <sup>(1)</sup>	Frequency offset	_	_	-123	_	_	-123	_	_	-123	dBc/Hz	
Transmitter REFCLK Total Jitter <sup>(1)</sup>	= 1 MHz – 8 MHZ	_	_	42.3	_	_	42.3	_	_	42.3	ps	
R <sub>ref</sub>	_	_	2000 ± 1%	_	_	2000 ± 1%	_	_	2000 ± 1%	_	Ω	
Transceiver Clock												
cal_blk_clk Clock frequency	_	10	_	125	10	_	125	10	_	125	MHz	
fixedclk Clock frequency	PCIe Receiver Detect	_	125	_	_	125	_	_	125	_	MHz	
reconfig_clk clock frequency	Dynamic reconfiguration clock frequency	2.5/ 37.5 <i>(2)</i>		50	2.5/ 37.5 <i>(2)</i>	_	50	2.5/ 37.5 <i>(2)</i>	_	50	MHz	
Delta time between reconfig_clk	_		_	2	_		2			2	ms	
Transceiver block minimum power-down pulse width	_	_	1	_	_	1	_	_	1	_	μs	